

Tolerances

Trace Tolerance (based on design review)	+ / - .0005"
Internal Drill to C _μ	.010"
Pad Over FHS	.004" Class 2 .005" Class 3
Soldermask Clearance Over PAD Size	.002"
From C _μ to the Edge of the Board	.010"
Impedance	+ / - 10%

LAMINATION

Board Thickness	+ / - 10%
Layer to Layer Registration	.004"

DRILL & ROUTE

Route	Laser: + / - .002" Mechanical: + / - .005"
Inside Radius	.015"
Minimum Slot Width	.021"
Drill Positioning	+ / - .002"
From C _μ To The Edge of the Board	.010"
Impedance	+ / - 10%

Capabilities

- 3 mil Trace Width
- 3 mil Air Gap
- IPC Class 3 Space
- Flying Probe Net List Test
- Differential Impedance
- TDR Testing
- Automatic Optical Inspection

LAMINATION

- 1 to 30 Layers
- Vacuum Lamination
- Sequential Lamination

DRILL & ROUTE

- Counter Sinks
- Counter Bores
- Scoring / Route & Retain
- Laser Route
- Blind Vias / Buried Vias
- Stacked Vias
- Plated Edges
- Castellations

MATERIALS

- Dupont Pyralux
- RF and High Speed Materials
- Mix Materials / FR-4 Teflon
- Metal Back Boards (LED / Power Distribution)
- Heavy C_μ 6 oz.

CERTIFICATIONS

- ISO / AS 9100
- MIL-SPEC 31032
- ITAR

VIA FILL CAPABILITIES

- Conductive Via Fill
- Cu Plate Via Fill (Micro Vias)
- Non-Conductive Via Fill

LEAD TIMES

Standard Rigid
10-15 days

Flex
15 Days

Multilayer Flex & Rigid-Flex
20 Days

SURFACE FINISHES

- ENIG
- ENEPIG
- Hard & Soft Bondable Gold
- HAL Leaded
- Lead Free Solder
- Immersion Silver